



20V N-Channel Trench Power MOSFET

General Description

The SJD20N030 uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a wide variety of applications.

Features

- Low Gate Charge
- 100% UIS Tested, 100% DVDS Tested
- High Power and current handling capability
- Lead free product is acquired

Application

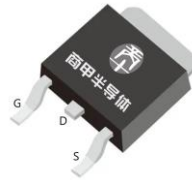
- PWM Applications
- Load Switch
- Power Management

Key Performance Parametes

Parameter	Value	Unit
V_{DS}	20	V
$R_{DS(ON_TYP)}$	2.9	mΩ
I_D	93	A
Q_G	38	nC



Schematic Diagram



TO-252(DPAK) view



Package Marking and Ordering Information

Device/Ordering Code	Marking	Package	Packing	Reel Size	Tape width	Quantity
SJD20N030	SJD20N030	TO-252	Tape	\	\	2500 Pcs

Table 1. Absolute Maximum Ratings ($T_C=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V_{DS}	Drain-Source Voltage ($V_{GS}=0\text{V}$)	20	V
V_{GS}	Gate-Source Voltage ($V_{DS}=0\text{V}$)	± 12	V
I_D	Drain Current-Continuous($T_C=25^{\circ}\text{C}$)	93	A
	Drain Current-Continuous($T_C=100^{\circ}\text{C}$)	59	A
$I_{DM}(\text{pluse})$	Drain Current-Continuous@ Current-Pulsed (Note 1)	372	A
P_D	Maximum Power Dissipation($T_C=25^{\circ}\text{C}$)	46	W
	Maximum Power Dissipation($T_C=100^{\circ}\text{C}$)	18	W
E_{AS}	Avalanche energy (Note 2)	196	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 150	$^{\circ}\text{C}$

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to- Case		2.7	$^{\circ}\text{C/W}$



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Table 3. Electrical Characteristics ($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250μA	20			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =20V, V _{GS} =0V T _J =25℃			1	μA
		V _{DS} =20V, V _{GS} =0V T _J =125℃			100	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±12V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	0.5		1	V
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =20A		99		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =4.5V, I _D =20A T _J =25℃		2.9	3.8	mΩ
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =2.5V, I _D =15A T _J =25℃		3.4	4.5	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =10V,V _{GS} =0V, f=1.0MHz		3022		pF
C _{oss}	Output Capacitance			359		pF
C _{rss}	Reverse Transfer Capacitance			39.2		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1.0MHz		1.7		Ω
Switching Parameters						
t _{d(on)}	Turn-on Delay Time	V _{GS} =4.5V, V _{DS} =10V, R _L =0.5Ω, R _{GEN} =3Ω		10		nS
t _r	Turn-on Rise Time			5.4		nS
t _{d(off)}	Turn-Off Delay Time			48		nS
t _f	Turn-Off Fall Time			5.5		nS
Q _g	Total Gate Charge	V _{GS} =4.5V, V _{DS} =10V, I _D =20A		38		nC
Q _{gs}	Gate-Source Charge			5.2		nC
Q _{gd}	Gate-Drain Charge			8		nC
Source-Drain Diode Characteristics						
I _{SD}	Source-Drain Current (Body Diode)				93	A
V _{SD}	Forward on Voltage (Note 3)	V _{GS} =0V, I _S =20A			1	V
t _{rr}	Reverse Recovery Time	I _F =20A, dI/dt=100A/μs		15.8		ns
Q _{rr}	Reverse Recovery Charge	I _F =20A, dI/dt=100A/μs		6.3		nC

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

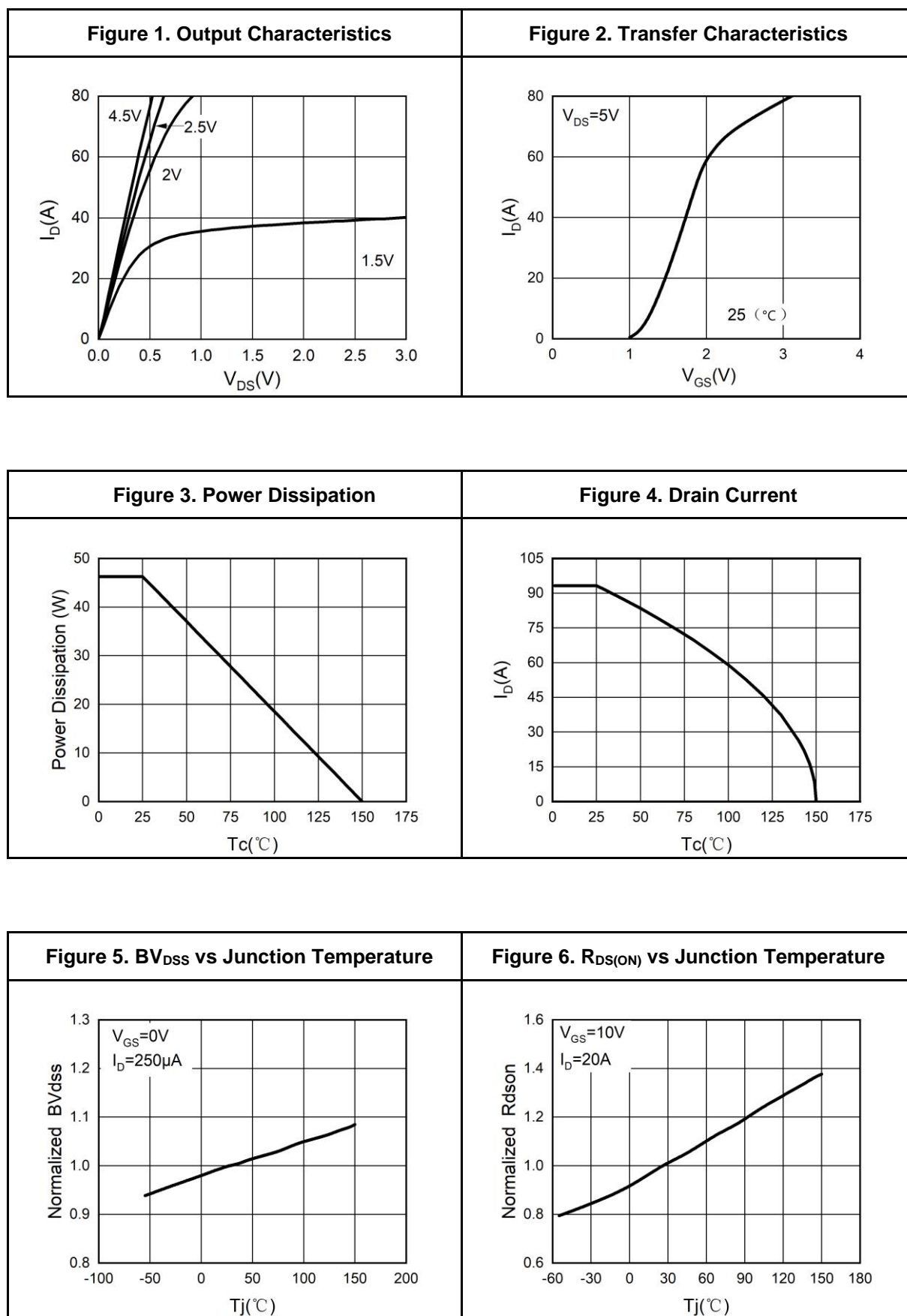
Notes 2.EAS condition: $T_J=25^{\circ}\text{C}$, $V_{DD}=10V$, $V_G=10V$, $R_g=25\Omega$, $L=0.5\text{mH}$.

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.



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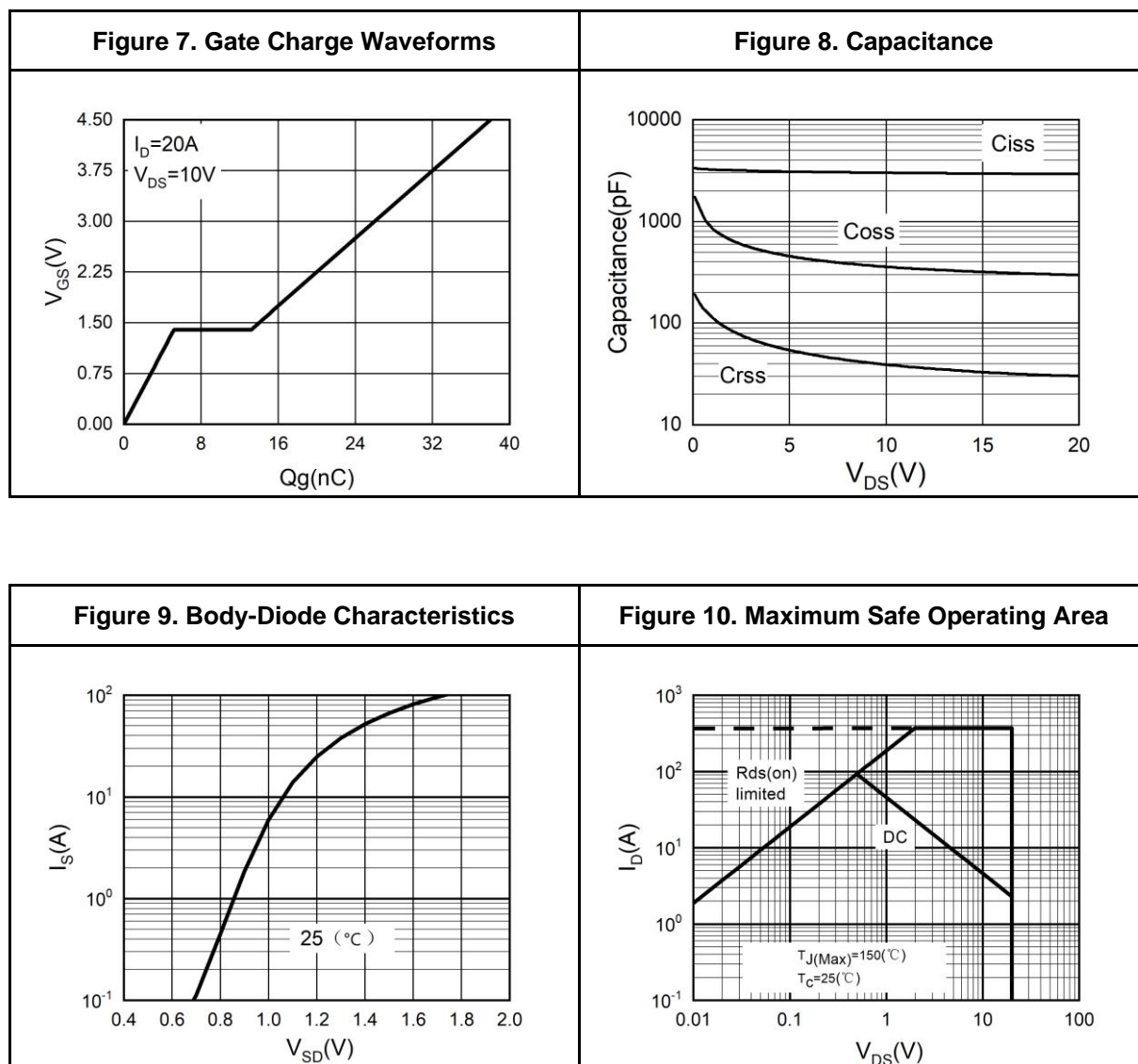
Typical Electrical And Thermal Characteristics (Curves)





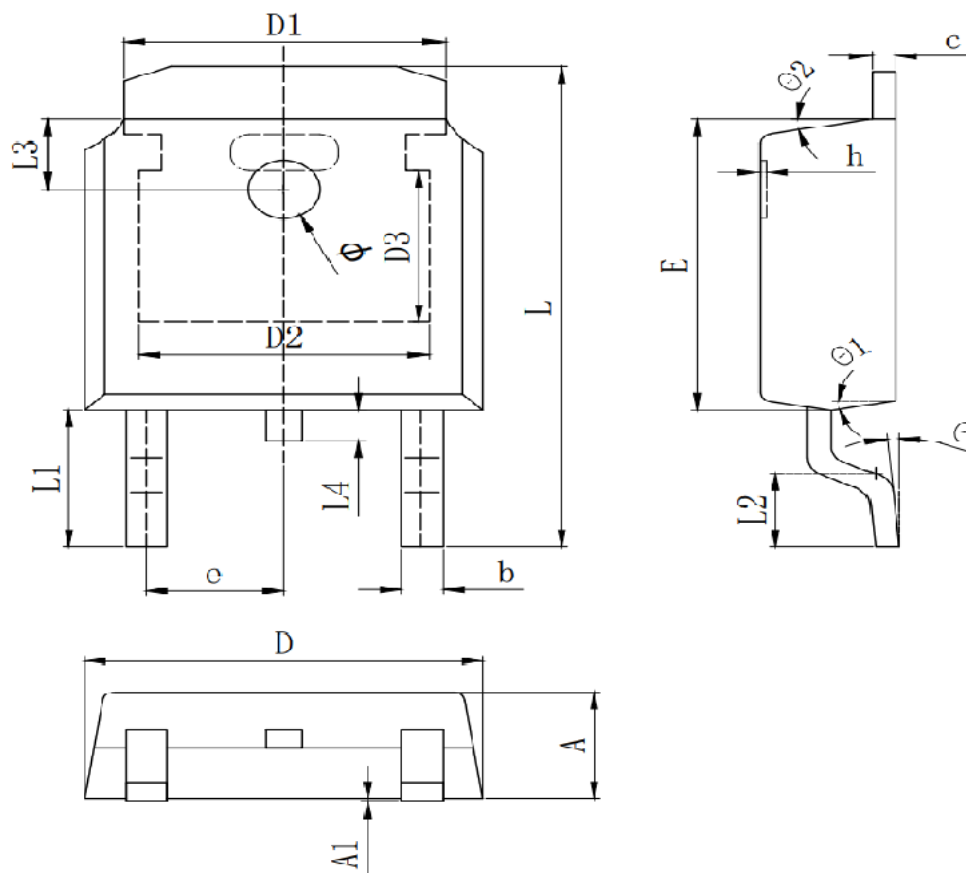
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Typical Electrical And Thermal Characteristics (Curves)





TO-252 Package Information



Symbol	Dimensions In Millimeters		
	Min.	Typ.	Max.
A	2.200	2.300	2.400
A1	0.000		0.127
b	0.640	0.690	0.740
c(电镀后)	0.460	0.520	0.580
D	6.500	6.600	6.700
D1	5.334 REF		
D2	4.826 REF		
D3	3.166 REF		
E	6.000	6.100	6.200
e	2.286 TYP		
h	0.000	0.100	0.200
L	9.900	10.100	10.300
L1	2.888 REF		
L2	1.400	1.550	1.700
L3	1.600 REF		
L4	0.600	0.800	1.000
Φ	1.100	1.200	1.300
θ	0°		8°
$\theta 1$	9° TYP		
$\theta 2$	9° TYP		



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